

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SanDisk Corporation	04/04/2011
RECEIVING PARTY DATA	
Name:	SanDisk Technologies Inc.
Street Address:	6900 North Dallas Parkway
Internal Address:	Two Legacy Town Center
City:	Plano
State/Country:	TEXAS
Postal Code:	75024
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7875996
CORRESPONDENCE DATA	
Fax Number:	(408)801-9019
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	4088012863
Email:	simona.benjamin@sandisk.com
Correspondent Name:	SanDisk Corporation
Address Line 1:	601 Mccarthy Boulevard
Address Line 2:	Patent Department/Simona Benjamin
Address Line 4:	Milpitas, CALIFORNIA 95035
ATTORNEY DOCKET NUMBER:	SDA-1291Y-US
NAME OF SUBMITTER:	Simona Benjamin
Total Attachments: 5 source=page 19#page1.tif source=page 19#page2.tif source=page 19#page3.tif source=page 19#page4.tif source=page 19#page5.tif	

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PATENT
REEL: 026278 FRAME: 0626

ASSIGNMENT

WHEREAS, SanDisk Corporation, a Delaware corporation, doing business at 601 McCarthy Boulevard, Milpitas, CA 95035 (hereinafter referred to as **ASSIGNOR**), holds right, title and interest throughout the world in and to the patents and patent applications set forth in the attached Exhibit A, together with all divisions, continuations, or continuations-in-part thereof, and all patents issuing thereon including reissues, renewals, substitutions, re-examinations and extensions thereof, and any and all corresponding foreign patents and patent applications (hereinafter referred to as, collectively, **THE ASSIGNED PATENT RIGHTS**);

WHEREAS, SanDisk Technologies Inc., a Texas corporation, doing business at Two Legacy Town Center, 6900 North Dallas Parkway, Plano, Texas 75024, (hereinafter referred to as **ASSIGNEE**), is desirous of acquiring the full and exclusive right, title and interest in **THE ASSIGNED PATENT RIGHTS**;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, **ASSIGNOR** hereby assigns, transfers and conveys unto the said **ASSIGNEE**, and **ASSIGNEE** accepts, all of **ASSIGNOR**'s right, title and interest throughout the world in and to **THE ASSIGNED PATENT RIGHTS** and to all Letters Patent or applications or similar legal protection, not only in the United States and its territorial possessions, but in all countries foreign thereto to be obtained for **THE ASSIGNED PATENT RIGHTS**, and to any continuation, division, renewal, substitute or reissue thereof or any legal equivalent thereof in the United States or a foreign country for the full term or terms for which the same may be granted, including all priority rights under the International Convention; and **ASSIGNOR** hereby authorizes and requests the United States Commissioner of Patents and Trademarks and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for **THE ASSIGNED PATENT RIGHTS** to **ASSIGNEE** in accordance with the terms of this **ASSIGNMENT** but subject to reserved rights including but not limited to those previously retained by, granted to, or owned by, the United States government, educational institutions or both and hereby transfers and conveys all rights of action, power and benefit belonging to or accruing from **THE ASSIGNED PATENT RIGHTS** including the right to undertake proceedings to recover past and future damages and claim all other relief in respect of any acts of infringement thereof whether such acts shall have been committed before or after the date of this assignment.

No other rights, immunities, or licenses, including, without limitation, any rights to any intellectual property owned, controlled or licensable by **ASSIGNOR** are granted or assigned to **ASSIGNEE** under this **ASSIGNMENT**, either expressly or by implication, estoppel, or otherwise, other than the rights expressly recited herein.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would knowingly conflict with this Agreement;

ASSIGNOR further covenants that **ASSIGNEE** will, upon its lawful request, reasonably be provided with all pertinent facts and documents relating to **THE ASSIGNED PATENT RIGHTS** and legal equivalents as may be known and reasonably accessible to **ASSIGNOR** and that **ASSIGNOR** will testify as to the same in any administrative contest or litigation related thereto and will promptly execute and deliver to **ASSIGNEE** or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce **THE ASSIGNED PATENT RIGHTS** and said equivalents in the United States or in any foreign country, which may be necessary or desirable to carry out the purposes thereof.

IN TESTIMONY WHEREOF, I hereunto set my hand as of the date indicated below.

SANDISK CORPORATION

Dated: 4th April 2011

Judy Bruner
Name: Judy Bruner
Title: EVP and CFO

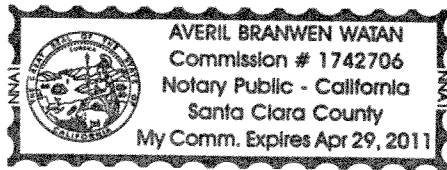
STATE OF California)
COUNTY OF Santa Clara) ss.

On this 4th day of April, 2011, before me Averil Branwen Watan (Notary Public), the undersigned Notary Public, personally appeared Judy Bruner,

who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



Signature: Averil Branwen Watan
Signature of Notary Public

We accept the Assignment

SANDISK TECHNOLOGIES INC.

Dated: 4/4/11

James F. Brelsford
Name: James F. Brelsford
Title: President and Secretary

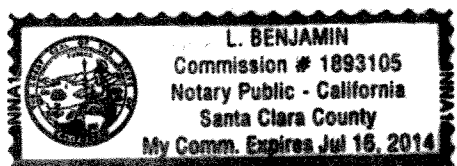
STATE OF California)
COUNTY OF Santa Clara) ss.

On this 4 day of April, 2011, before me L. Benjamin, the undersigned Notary Public, personally appeared JAMES F. BRELSFORD

who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



Signature: L. Benjamin
Signature of Notary Public

Exhibit A

FILE #	INVENTORS	TITLE	COUNTRY	STATUS	SER #	FILING DATE	PAT #	ISSUE DATE
SDA-1273-a-US	Suresh Upadhyayula, Hem Takiar	SEMICONDUCTOR PACKAGE INCLUDING FLIP CHIP CONTROLLER AT BOTTOM OF DIE STACK	US	Pending	12986927	7-Jan-11		
SDA-1273-US	Suresh Upadhyayula, Hem Takiar	SEMICONDUCTOR PACKAGE INCLUDING FLIP CHIP CONTROLLER AT BOTTOM OF DIE STACK	US	Issued	11965702	27-Dec-07	7867819	11-Jan-11
SDA-1274-US	Suresh Upadhyayula, Robert C Miller, Hem Takiar, Steven T. Sprouse, Lily (Ka Ian) Yung	Low Profile Wire Bonded USB Device	US	Published	11965691	27-Dec-07		
SDA-1276-US	Andrew Tomlin, Dennis Ea, Daniel Tuers	Memory Device and Method for Performing a Write-Abort-Safe Firmware Update	US	Published	12005727	28-Dec-07		
SDA-1277-II-US	Fabrice Jogand-Coulomb, Robert C Chang	Memory Device and Method for Content Virtualization	US	Published	12777399	11-May-10		
SDA-1277-I-US	Fabrice Jogand-Coulomb, Robert C Chang	Memory Device and Method for Content Virtualization	US	Published	12777385	11-May-10		
SDA-1277-US	Fabrice Jogand-Coulomb, Robert C Chang	Memory Device and Method for Content Virtualization	US	Published	12005728	28-Dec-07		
SDA-1279-US	Haluk Kent Tanik, Robert C Chang, Po Yuan, Bahman Qawami, Farshid Sabet-Sharghi	Method and System for Transferring Data and Instructions through a Host File System	US	Published	11967622	31-Dec-07		
SDA-1280-US	Po Yuan, Javier Canis Robles, Mei Yan, Fabrice Jogand-Coulomb, Ahmet Altay, Bahman Qawami, Patricia Dwyer, Robert C Chang, Oktay Rasizade, Farshid Sabet-Sharghi	Method and System for Creating and Accessing a Secure Storage Area in a Non-Volatile Memory Card	US	Pending	11967641	31-Dec-07		
SDA-1281-US	Kevin Conley, Daniel Schreiber, Avi Shmuel, Noam Kedem	Powerfully Simple Digital Media Player and Methods for Use Therewith	US	Published	11967861	31-Dec-07		
SDA-1282-US	Jason Lin, Steven Cheng, Shai Traister	System, Method and Memory Device Providing Data Scrambling Compatible With On-Chip Copy Operation	US	Published	12345921	30-Dec-08		
SDA-1283-US	Paul Paternoster, Vaibhavi Sabharanjak, Po-Shen Lai	Integrated Circuit and Manufacturing Process Facilitating Selective Configuration for Electromagnetic Compatibility	US	Published	11967880	31-Dec-07		
SDA-1284-US	Po-Shen Lai, Vaibhavi Sabharanjak, Ralph Heron, Lakhdar Iguelmamene	Extending Drive Capability in Integrated Circuits Utilizing Programmable-Voltage Output Circuits	US	Issued	11967885	31-Dec-07	7812639	12-Oct-10
SDA-1285-US	Ekram Hossain Bhuiyan	Current Mirror Device and Method	US	Pending	11954924	12-Dec-07		
SDA-1286-US	Steven T. Sprouse, Lily (Ka Ian) Yung	Duplicate SD Interface Memory Card Controller	US	Issued	11963519	21-Dec-07	7921255	5-Apr-11
SDA-1289-US	Baojing Liu, Matthew Davidson, Vladimir Kovalev	TEST MODE SOFT RESET CIRCUITRY AND METHODS	US	Allowed	12019534	24-Jan-08		
SDA-1290X-US	Steve Chi, Yongliang Bill Wang, Ekram Hossain Bhuiyan, Daniel Nguyen, Vincent Conditto, Po-Shen Lai	Self-Configurable Multi-Regulator ASIC Core Power Delivery	US	Issued	12005056	21-Dec-07	7859134	28-Dec-10
SDA-1291Y-US	Daniel Nguyen, Steve Chi, Po-Shen Lai	Multi-Regulator Power Delivery System for ASIC Cores	US	Issued	12005144	21-Dec-07	7875996	25-Jan-11
SDA-1292X-US	Hem Takiar, Shrikar Bhagath, Cheeman Yu, Chih Chin Liao	METHOD OF FABRICATING STACKED SEMICONDUCTOR PACKAGE WITH LOCALIZED CAVITIES FOR WIRE BONDING	US	Published	12165297	30-Jun-08		
SDA-1292Y-US	Hem Takiar, Shrikar Bhagath, Cheeman Yu, Chih Chin Liao	STACKED SEMICONDUCTOR PACKAGE WITH LOCALIZED CAVITIES FOR WIRE BONDING	US	Published	12165320	30-Jun-08		